



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model

[List multiple models if applicable.]

HP Compaq L2206tmp 21.5-inch Touch Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		6
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screw driver of "+" type	200mm
Description #2 Hexagonal nut screw driver for DVI and D-SUB connector	200mm
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

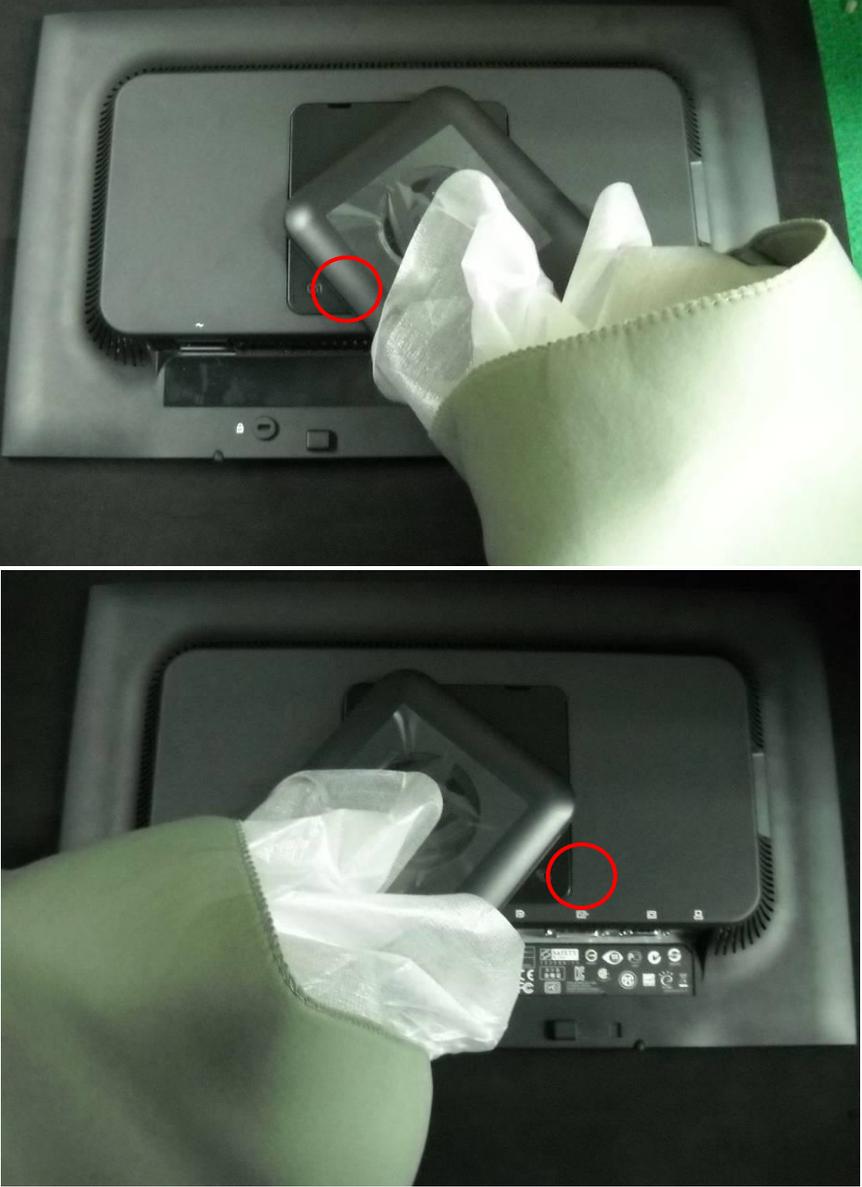
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

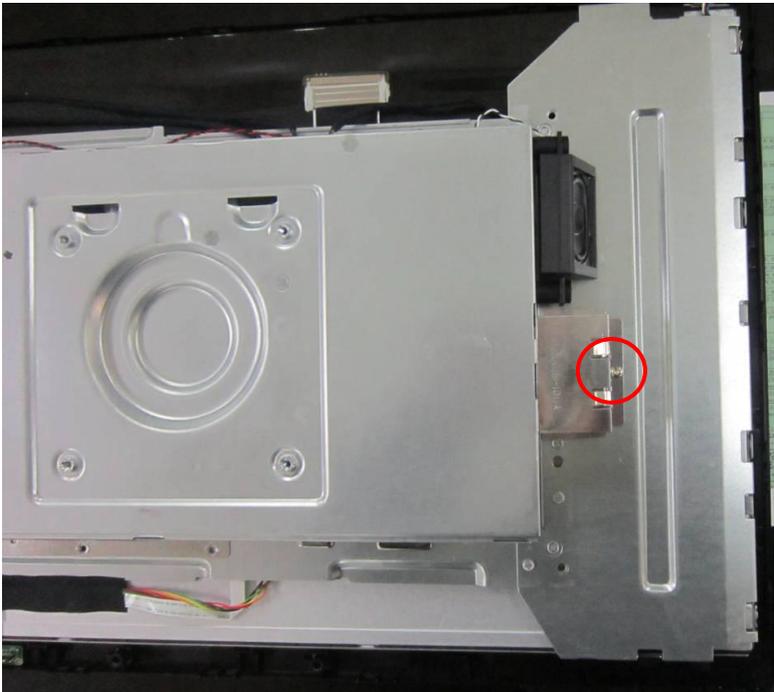
1. Dismantle the screws of stand, get down the stand
2. Dismantle the cover of monitor
3. Dismantle the button, pull out the pin of KEPC board ,get down the KEPC board
4. Dismantle mainframe
5. Dismantle BEZEL
6. Dismantle the screws of PANEL
7. Pull out the PIN of lamp
8. Pull out the PIN of LVDS cable, separate the mainframe and PANEL
9. Dismantle the power board screws
10. Dismantle the VGA screws
11. First: Tear off the adhesive tape;
12. Second: Pull out the connector PIN which connect PWPC and main board;
13. Third: Take off both boards
14. Pull out the pin of KEPC cable
- 15.
- 16.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

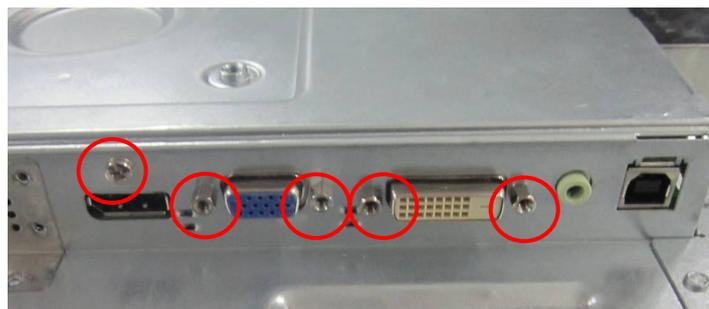
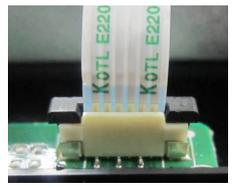
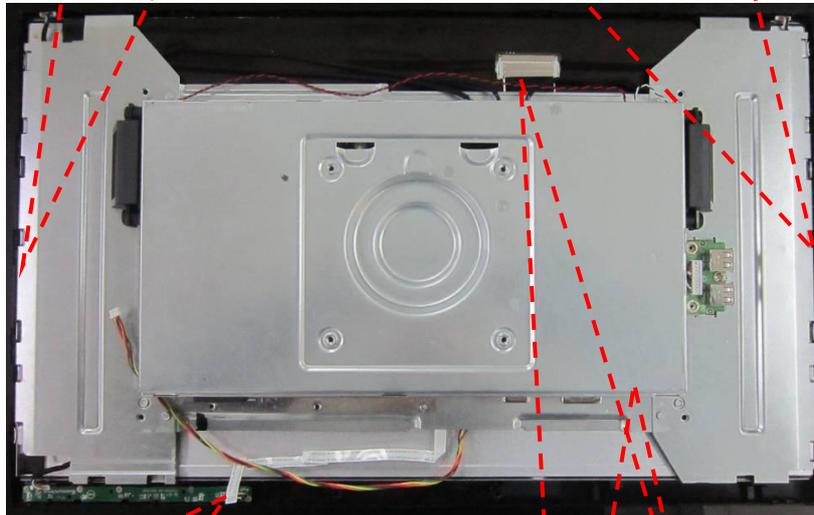
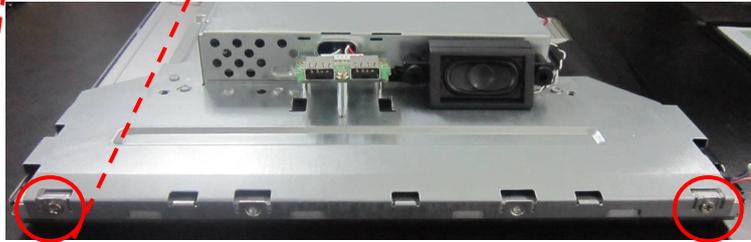
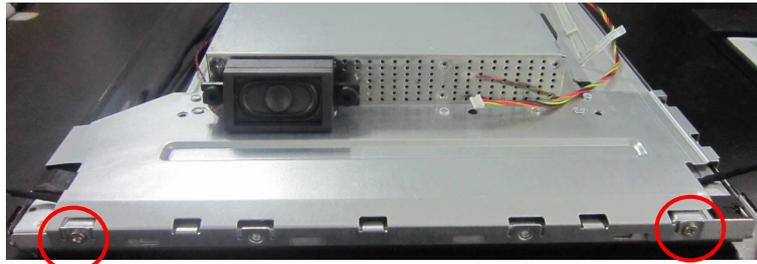
Pls. refer the attached:

Mechanical Instructions

Step	Figure	Description
Preparation	 A photograph showing an HP monitor on a workbench. The monitor is black with the HP logo at the bottom center. It is positioned on a dark surface, and various cables and components are visible in the background.	The monitor
Remove the HINGE ASS'Y	 Two photographs showing the back of the monitor. The top photo shows a red circle highlighting a screw on the left side of the hinge assembly. The bottom photo shows a red circle highlighting a screw on the right side of the hinge assembly. A white plastic bag is visible in the foreground of both photos.	Remove the screws to remove the HINGE ASS'Y.

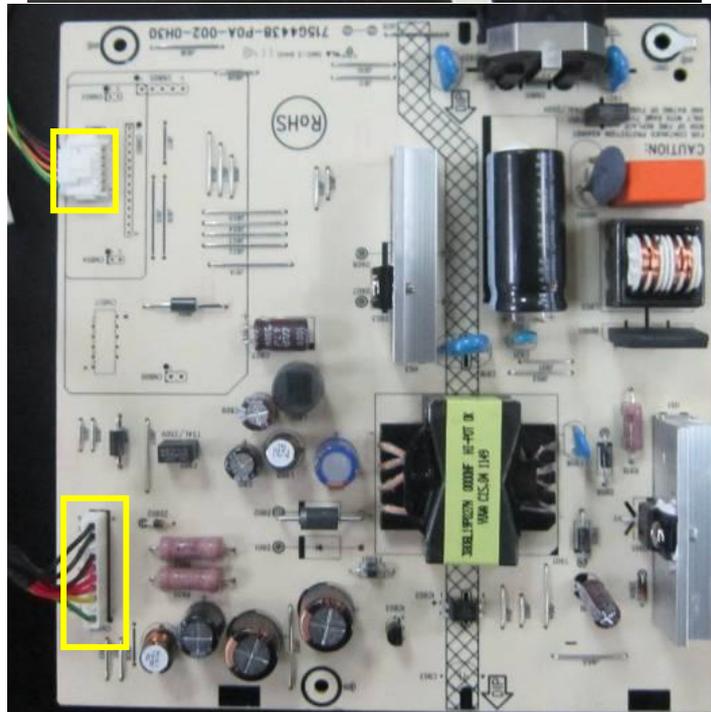
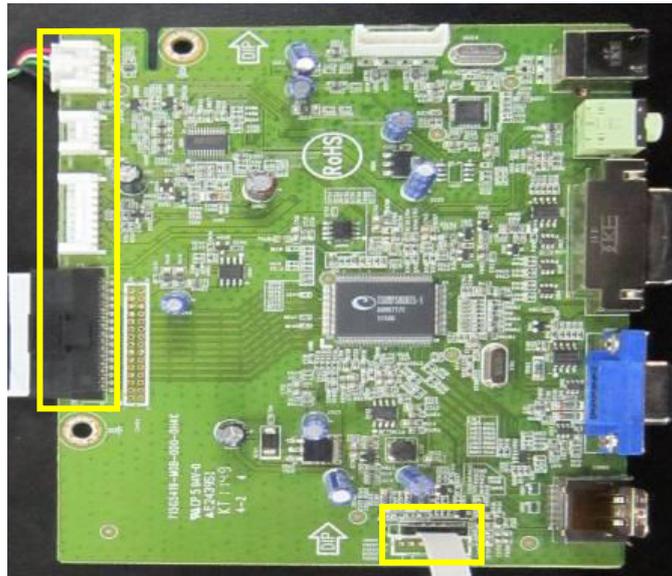
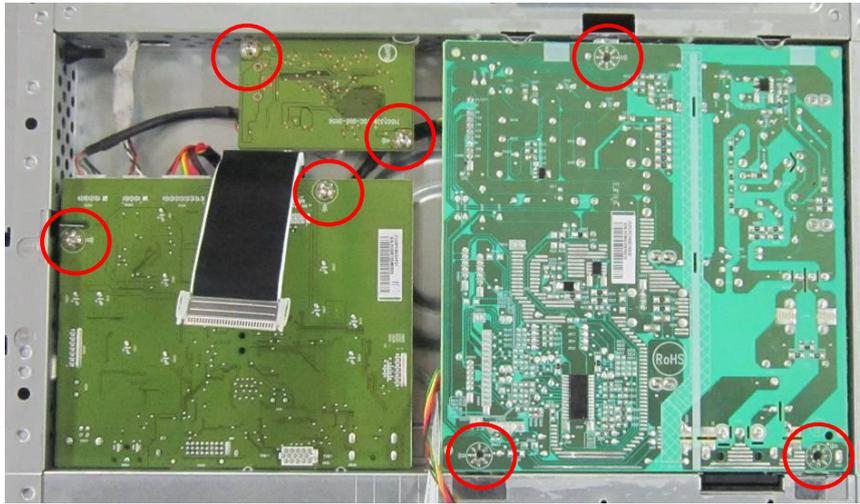
<p>The HINGE ASS'Y</p>		<p>The HINGE ASS'Y</p>
<p>Remove the REAR_COVER</p>		<p>Remove the REAR_COVER</p>
<p>Remove the SHIELD USB</p>		<p>Remove the screws to remove the SHIELD USB.</p>

Separate the
MAINFRAME
and PANEL



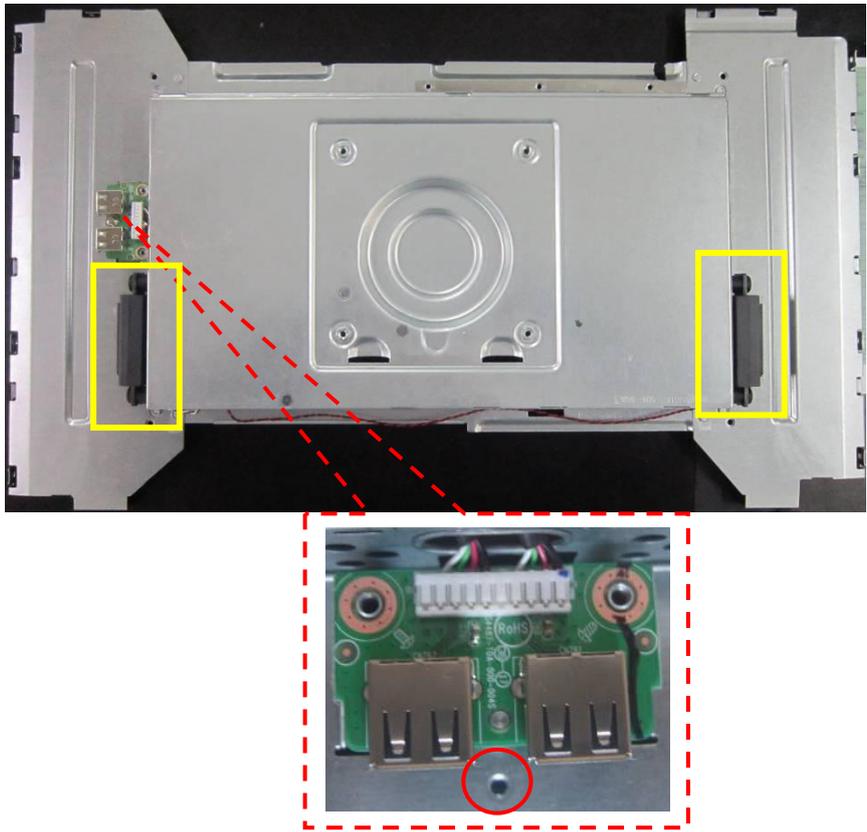
Disconnect the
connectors and
remove the
screws to
separate the
MAINFRAME
and PANEL.

**Remove the
MAIN BOARD
and POWER
BOARD**



Remove the screws and disconnect the connectors to remove the MAIN BOARD and POWER BOARD.

**Remove the
SPEAKERS
and USB
BOARD**



Remove the screws to remove the USB BOARD and SPEAKERS.

The bezel



The bezel

The panel



The panel